



Material Content Data Sheet



Sales Product Name		SP270-25-256-0		Issued		26. September 2017		
MA#		MA001007520						
Package		PG-DSOSP-14-64		Weight*		610.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.623	2.07	2.07	20693	20693
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		72	
	non noble metal	zinc	7440-66-6	0.176	0.03		288	
	non noble metal	iron	7439-89-6	3.511	0.58		5756	
wire	non noble metal	copper	7440-50-8	142.572	23.37	23.99	233716	239832
	noble metal	gold	7440-57-5	0.941	0.15	0.15	1542	1542
	encapsulation	organic material	carbon black	1333-86-4	0.878	0.14		1439
encapsulation	plastics	epoxy resin	-	47.409	7.77		77717	
	inorganic material	silicondioxide	60676-86-0	390.684	64.05	71.96	640445	719601
leadfinish	non noble metal	tin	7440-31-5	4.526	0.74	0.74	7419	7419
plating	noble metal	silver	7440-22-4	2.637	0.43	0.43	4322	4322
glue	plastics	maleimide resin	-	0.804	0.13		1318	
	noble metal	silver	7440-22-4	3.217	0.53	0.66	5273	6591
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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